Trelleborg EP661 is a two component, low viscosity, epoxy adhesive system designed for use up to temperatures of 230 °C. It may be used for many diverse bonding applications but is most suitable as a thin bond line adhesive for blocking up Trelleborg epoxy boards. The adhesive system gels at room temperature, but requires a post cure to achieve maximum properties.

Features & Benefits
- Low viscosity
- High heat stability
- High temperature resistance

Applications
- EP661 is designed as a thin bond line adhesive for bonding epoxy boards and offers excellent thermal and mechanical performance.
- It is suitable for use up to 230 °C.

Product Sizes
EP661 is available in a 1 Kg kit.

Storage
Adhesive EP661 and hardener EP661 should be stored in original containers at a temperature between 15 and 25 °C. The product may crystallize during storage. If crystallized, warm to 55 – 65 °C until dissolution, then mix well. Both components, if stored in the specified conditions, have a shelf life of 12 months from the date of production.

Health & Safety
Eye protection and gloves should be worn when working with Trelleborg EP661.
Please refer to the Trelleborg Material Safety Data Sheet.

<table>
<thead>
<tr>
<th>Product</th>
<th>Material</th>
<th>Aspect</th>
<th>Color</th>
<th>Mix Ratio (pbw)</th>
<th>Viscosity</th>
<th>Gel Time* (150 g)</th>
</tr>
</thead>
<tbody>
<tr>
<td>EP661 Adhesive</td>
<td>Epoxy formulation</td>
<td>Liquid</td>
<td>-</td>
<td>100</td>
<td>42,000 mPas</td>
<td>-</td>
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<tr>
<td>EP661 Hardener</td>
<td>Amine</td>
<td>Liquid</td>
<td>-</td>
<td>40</td>
<td>2,600 mPas</td>
<td>-</td>
</tr>
<tr>
<td>Mixture</td>
<td>formulation</td>
<td>Liquid</td>
<td>Dark Amber</td>
<td>-</td>
<td>9,200 mPas</td>
<td>130 minutes</td>
</tr>
</tbody>
</table>

*data measured at 25 °C
**EP661 Processing Guidelines**

**Preparation of Substrates**
Read the Material Safety Data Sheet before use. Substrate surfaces must be cleaned and dried to remove traces of dust, dirt, oils or release agent before applying EP661. If necessary, degrease with 1-bromopropane or other suitable solvent. Models, molds and parts to be assembled must withstand the recommended post-cure cycle temperature.

**Mixing and Application**
Always use clean, dry tools for mixing and applying. Adhesive EP661 must be mixed with hardener EP661 in the exact mix ratio by weight indicated. Both components must be at room temperature (20 – 25 °C).

Mix until smooth, paying attention to the material on the edges of the container and not to incorporate too much air.

For gluing and repair of epoxy boards intended for applications at elevated temperatures, the use of vacuum is recommended to avoid the retention of any air pockets.

**Polymerization and Post-Curing**
High temperature epoxy systems require an elevated temperature post cure to enable them to develop their full physical and temperature properties.

A full cure is obtained after 72 hours at 20 °C but to allow the material to reach its highest thermal stability, a thermal cycle of 4 hours at 120 °C is recommended.

**Contact Us**
Trelleborg’s Applied Technologies division is an industry expert in delivering innovative and reliable solutions that maximize performance for our customers. Our vast range of specialized, customizable materials ensure peace of mind at every stage of your project. With reliable and efficient project management and manufacturing we endeavor to take performance to new levels by achieving your goals safely, on time and within scope.

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**MECHANICAL PROPERTIES**

<table>
<thead>
<tr>
<th>Property</th>
<th>Value</th>
<th>Standard</th>
</tr>
</thead>
<tbody>
<tr>
<td>Shore Hardness</td>
<td>85 D</td>
<td>ISO 868</td>
</tr>
<tr>
<td>Flexural Strength</td>
<td>60 MPa</td>
<td>ISO 178</td>
</tr>
<tr>
<td>Flexural Modulus</td>
<td>2,900 MPa</td>
<td>ISO 178</td>
</tr>
<tr>
<td>Tensile Strength</td>
<td>81 MPa</td>
<td>ISO 527-1</td>
</tr>
<tr>
<td>Compressive Strength</td>
<td>176 MPa</td>
<td>ISO 604</td>
</tr>
<tr>
<td>Coefficient of Thermal Expansion</td>
<td>26.7 x 10⁻⁶ m/m/°C</td>
<td>ASTM D648</td>
</tr>
<tr>
<td>HDT, Post Cure</td>
<td>235 °C</td>
<td></td>
</tr>
</tbody>
</table>